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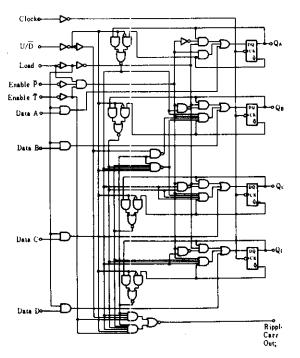
This synchronous presettable decade counter features an internal carry look-ahead for cascading in high-speed counting applications. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the countenable inputs and internal gating. This mode of operation helps eliminate the output counting spikes that are normally associated with asynchronous (ripple-clock) counters.

A buffered clock input triggers the four master-slave flipflops on the rising (positive-going) edge of the clock waveform. This counter is fully programmable; that is, the outputs may each be preset to either level. The load input circuitry allows loading with the carry-enable output of cascaded counters. As loading is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the data inputs after the next clock pulse.

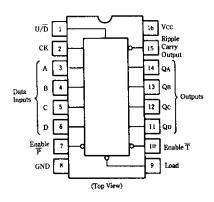
The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are two count enable inputs and a carry output. Both count enable inputs (P

and T) must be low to count. The direction of the count is determined by the level of the up/down input. When the input is high, the counter counts up; when low, it counts down. Input T is fed forward to enable the carry output. The carry output thus enabled will produce a low-level output pulse with a duration approximately equal to the high portion of the QA output when counting up and approximately equal to the low portion of the QA output when counting down. This low level overflow carry pulse can be used to enable successive cascaded stages. Transitions at the enable P or T inputs are allowed regardless of the level of the clock input. All inputs are diode-clamped to minimize transmission-line effects, thereby simplifying system design. This counter features a fully independent clock circuit. Changes at control inputs (enable P, Enable T, load, up/down) that will modify the operating mode have no effect until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) will be dictated solely by the conditions meeting the stable setup and hold times.

BLOCK DIAGRAM



PIN ARRANGEMENT



MRECOMMENDED OPERATING CONDITIONS

Item		Symbol	min	typ	max	Unit	
Output current		Іон		_	-400	μA	
Output current		Io _L			8	mA	
Clock frequency		fictork	0	_	25	MHz	
Clock pulse width		Ewice)	25	_		ns	
Setup time	Input Data, A, B, C, D	t.n.	25				
	Enable P, T		35		_	ns	
	Load		30	_	_		
	Up/Down		35		-		
Hold time		t _A	0		-	ns	

ELECTRICAL CHARACTERISTICS $(Ta = -20 \sim +75^{\circ}C)$

Item		Symbol	Test Conditions		typ*	max	Unit
Input voltage		V_{IH}		2	_	-	V
		VIL		-	_	0.8	V
Output voltage		V _{OH}	$V_{CC}=4.75$ V, $V_{IH}=2$ V, $V_{IL}=0.8$ V, $I_{OH}=-400$	μA 2.7	<u> </u>		v
		Vol	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}$ $\frac{I_{OL} = 4 \text{ mA}}{I_{OL} = 8 \text{ mA}}$			0.4	V
				-	_	0.5	V
Input current	$A, B, C, D, \overline{P}, U/\overline{D}$	IIH				20	
	Clock, T		Vcc-5.25V, V ₁ -2.7V		_	20	μA
	Load					40	
	A, B, C, D, \vec{P} , U/ \vec{D}	I _{1L}	Vcc-5.25V, V1-0.4V			-0.4	mA
	Clock, T					-0.4	
	Load				_	-0.8	
	$A, B, C, D, \overline{P}, U/\overline{D}$		Vcc-5.25V, Vi-7V			0.1	mA
	Clock, T	I_i				0.1	
	Load				_	0.2	
Short-circuit output current		Ios	$V_{CC} = 5.25 \text{V}$	20		-100	mA
Supply current **		Icc	Vcc - 5.25 V		20	34	mА
Input clamp voltage		Vix	V _{CC} = 4.75V, I _{LN} = -18mA	_	_	-1.5	v

^{*} VCC=5V, Ta=25°C

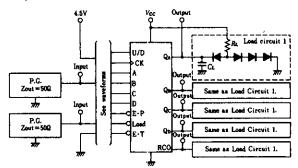
ISWITCHING CHARACTERISTICS ($V_{cc}=5V$, $T_a=25^{\circ}C$)

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum count frequency	f				25	32		MHz
Propagation delay time	t plh	Clock	Ripple	Cι = 15pF, Rι = 2kΩ	_	26	40	ns
	t PHL		Carry			40	60	
	I PLH	Clock	Q _A ~Q _D		_	18	27	ns
	t PHL					18	27	
	t plH	Enable T	Ripple			11	17	ns
	l phi		Carry		_	29	45	
	I PLH	Up/Down	Ripple			22	35	
	1 PHL		Carry			26	40	

^{**} ICC is measured after applying a momentary 4.5V, then ground, to the clock input with all other inputs grounded the outputs open.

TESTING METHOD

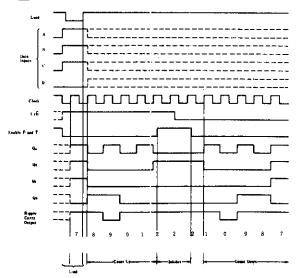
1) Test Circuit



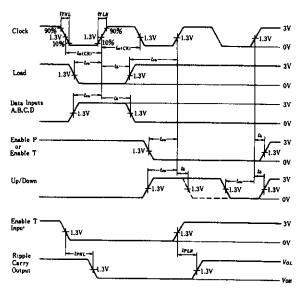
Notes) 1. C_L includes probe and jig capacitance.

2. All diodes are 1S2074 (H).

COUNT SEQUENCE

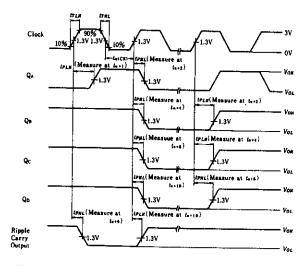


Waveform



Notes) 1. t_{PLH} and t_{PHL} from enable \overline{T} input to ripple carry output assume that the counter is at the maximum count (Q_A and Q_D high).

- 2. Propagation delay time from up/down to ripple carry must be measured with the counter at either a minimum or a maximum count. As the logic level of the up/down input is changed, the ripple carry output will follow. If the count is minimum (0) the ripple carry output transition will be in phase. If the count is maximum (9) the ripple carry output will be out of phase.
- 3. Input pulse: $t_{TLH} \le 15$ ns, $t_{THL} \le 6$ ns, PRR = 1MHz



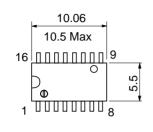
Notes) 1. Input pulse: $t_{TLH} \le 15$ ns, $t_{THL} \le 6$ ns, PRR = 1 MHz, duty cycle 50%.

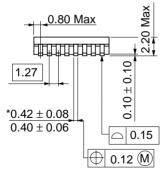
2. For f_{max} , $t_{TLH} = t_{THL} \le 2.5$ ns.

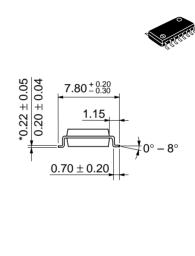
3. In is the bit-time when all outputs are low.

Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min $0.25^{+0.13}_{-0.05}$ 0.48 ± 0.10 2.54 ± 0.25 $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm







*Dimension including the plating thickness
Base material dimension

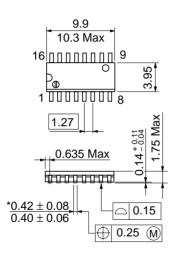
EIAJ Conforms
Weight (reference value) 0.24 g

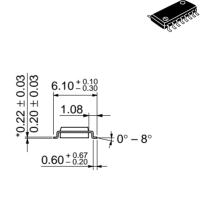
FP-16DA

Hitachi Code

JEDEC

Unit: mm





*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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